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**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q73159

Hien Boon TAN , et al.

Appln. No.: 10/721,384

Group Art Unit: 2826

Confirmation No.: 6008

Examiner: Alexander O. Williams

Filed: November 26, 2003

For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE AND METHOD OF  
MANUFACTURING THE PACKAGE

**AMENDMENT UNDER 37 C.F.R. § 1.111**

**MAIL STOP AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated April 22, 2005, within the shortened statutory period of three months as extended by two additional months on the basis of the accompanying petition and fee, please amend the above-identified application as follows on the accompanying pages.